File Number 1581

IRF820, IRF821, IRF822, IRF823

Power MOS Field-Effect Transistors

N-Channel Enhancement-Mode Power Field-Effect Transistors

2.0A and 2.5A, 450V-500V

$r_{DS}(on)$ = 3.0 Ω and 4.0 Ω

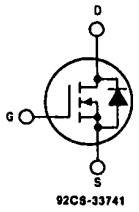
Features:

- *SOA is power-dissipation limited*
- *Nanosecond switching speeds*
- *Linear transfer characteristics*
- *High input impedance*
- *Majority carrier device*

The IRF820, IRF821, IRF822 and IRF823 are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

The IRF-types are supplied in the JEDEC TO-220AB plastic package.

N-CHANNEL ENHANCEMENT MODE



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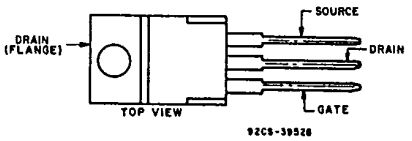
TERMINAL DIAGRAM

TERMINAL DESIGNATION



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JEDEC TO-220AB

Absolute Maximum Ratings

Parameter		IRF820	IRF821	IRF822	IRF823	Units
V_{DS}	Drain - Source Voltage ①	500	450	500	450	V
V_{DGR}	Drain - Gate Voltage (R_{GS} 20 KΩ) ①	500	450	500	450	V
I_D @ T_C = 25°C	Continuous Drain Current	2.5	2.5	2.0	2.0	A
I_D @ T_C = 100°C	Continuous Drain Current	1.5	1.5	1.0	1.0	A
I_{DM}	Pulsed Drain Current ③	10	10	8.0	8.0	A
V_{GS}	Gate - Source Voltage	±20				V
P_D @ T_C = 25°C	Max. Power Dissipation	40 (See Fig. 14)				W
	Linear Derating Factor	0.32 (See Fig. 14)				W/°C
I_{LM}	Inductive Current, Clamped	(See Fig. 15 and 16) L = 100μH				
		10	10	8.0	8.0	A
T_J T_{stg}	Operating Junction and Storage Temperature Range	-55 to 150				°C
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)				°C

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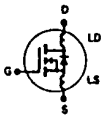
Electrical Characteristics @T_C = 25°C (Unless Otherwise Specified)

Parameter		Type	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain - Source Breakdown Voltage	IRF820 IRF822	500	-	-	V	V_{GS} = 0V
		IRF821 IRF823	450	-	-	V	I_D = 250μA
$V_{GS(th)}$	Gate Threshold Voltage	ALL	2.0		4.0	V	V_{DS} = V_{GS}, I_D = 250μA
I_{GSS}	Gate-Source Leakage Forward	ALL	-	-	500	nA	V_{GS} = 20V
I_{GSS}	Gate-Source Leakage Reverse	ALL	-	-	-500	nA	V_{GS} = -20V
I_{DSS}	Zero Gate Voltage Drain Current	ALL	-		250	μA	V_{DS} = Max. Rating, V_{GS} = 0V
			-	-	1000	μA	V_{DS} = Max. Rating x 0.8, V_{GS} = 0V, T_C = 125°C
$I_{D(on)}$	On State Drain Current ②	IRF820 IRF821	2.5	-	-	A	V_{DS} > $I_{D(on)}$ x $R_{DS(on)}$ max., V_{GS} = 10V
		IRF822 IRF823	2.0	-	-	A	
$R_{DS(on)}$	Static Drain-Source On-State Resistance ②	IRF820 IRF821	-	2.5	3.0	Ω	V_{GS} = 10V, I_D = 1.0A
		IRF822 IRF823	-	3.0	4.0	Ω	
g_{fs}	Forward Transconductance ②	ALL	1.0	1.75	-	S (℧)	V_{DS} > $I_{D(on)}$ x $R_{DS(on)}$ max., I_D = 1.0A
C_{iss}	Input Capacitance	ALL	-	300	400	pF	V_{GS} = 0V, V_{DS} = 25V, f = 1.0 MHz See Fig. 10
C_{oss}	Output Capacitance	ALL	-	75	150	pF	
C_{rss}	Reverse Transfer Capacitance	ALL	-	20	40	pF	
$t_{d(on)}$	Turn-On Delay Time	ALL	-	30	60	ns	V_{DD} = 0.5 BV_{DSS}, I_D = 1.0A, Z_o = 50Ω See Fig. 17 (MOSFET switching times are essentially independent of operating temperature.)
t_r	Rise Time	ALL	-	25	50	ns	
$t_{d(off)}$	Turn-Off Delay Time	ALL	-	30	60	ns	
t_f	Fall Time	ALL	-	15	30	ns	
Q_g	Total Gate Charge (Gate-Source Plus Gate Drain)	ALL	-	11	15	nC	V_{GS} = 10V, I_D = 3.0A, V_{DS} = 0.8 Max. Rating. See Fig. 18 for test circuit. (Gate charge is essentially independent of operating temperature.)
Q_{gs}	Gate-Source Charge	ALL	-	5.0	-	nC	
Q_{gd}	Gate-Drain ("Miller") Charge	ALL	-	6.0	-	nC	
L_D	Internal Drain Inductance	ALL	-	3.5	-	nH	Measured from the contact screw on tab to center of die.
			-	4.5	-	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
L_S	Internal Source Inductance	ALL	-	7.5	-	nH	Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.

Modified MOSFET symbol showing the internal device inductances.



Thermal Resistance

R_{thJC}	Junction to Case	ALL		-	3.12	C/W	
R_{thCS}	Case-to-Sink	ALL		1.0	-	C/W	Mounting surface flat, smooth, and greased.
R_{thJA}	Junction-to-Ambient	ALL	-	-	80	C/W	Free Air Operation

Source-Drain Diode Ratings and Characteristics

I_S	Continuous Source Current (Body Diode)	IRF820 IRF821	-	-	2.5	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier
		IRF822 IRF823	-	-	2.0	A	
I_{SM}	Pulse Source Current (Body Diode) ③	IRF820 IRF821	-	-	10	A	
		IRF822 IRF823	-	-	8.0	A	
V_{SD}	Diode Forward Voltage ②	IRF820 IRF821	-	-	1.6	V	T_C = 25°C, I_S = 2.5A, V_{GS} = 0V
		IRF822 IRF823	-	-	1.5	V	T_C = 25°C, I_S = 2.0A, V_{GS} = 0V
t_{rr}	Reverse Recovery Time	ALL	-	600	-	ns	T_J = 150°C, I_F = 2.5A, di_F/dt = 100 A/μs
Q_{RR}	Reverse Recovered Charge	ALL	-	3.5	-	μC	T_J = 150°C, I_F = 2.5A, di_F/dt = 100 A/μs
t_{on}	Forward Turn on Time	ALL	Intrinsic turn on time is negligible. Turn-on speed is substantially controlled by L_S + L_D				

① T_J = 25°C to 150°C. ② Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%. ③ Repetitive Rating: Pulse width limited by max. junction temperature See Transient Thermal Impedance Curve (Fig. 5).

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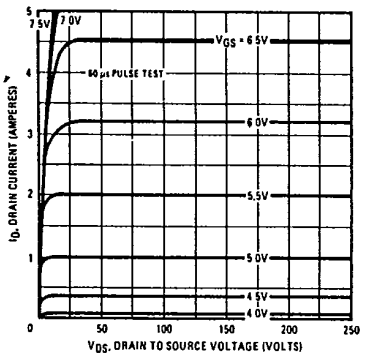

Fig. 1 – Typical Output Characteristics

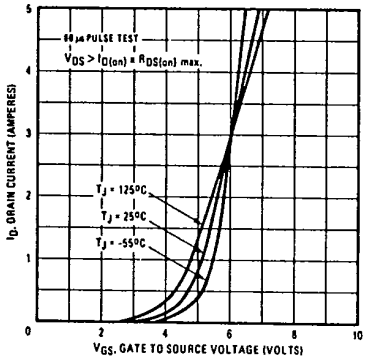

Fig. 2 – Typical Transfer Characteristics

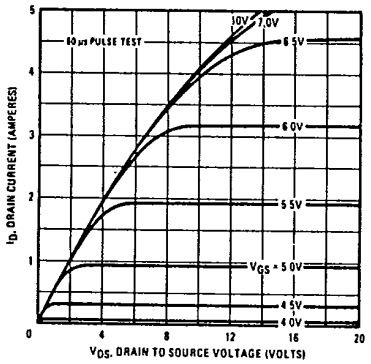

Fig. 3 – Typical Saturation Characteristics

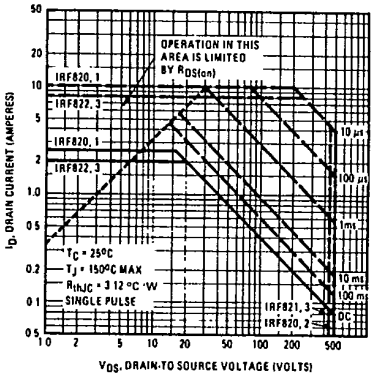

Fig. 4 – Maximum Safe Operating Area

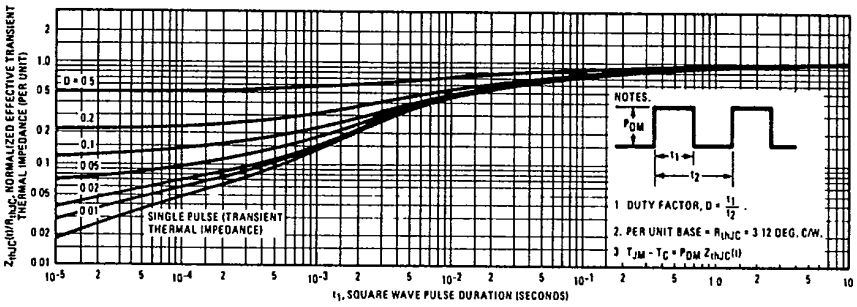

Fig. 5 – Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

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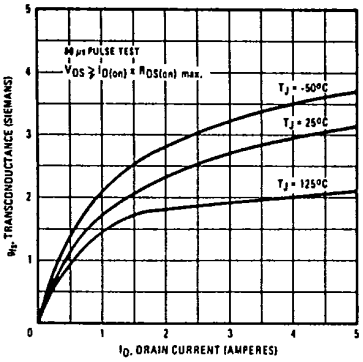

Fig. 6 – Typical Transconductance Vs. Drain Current

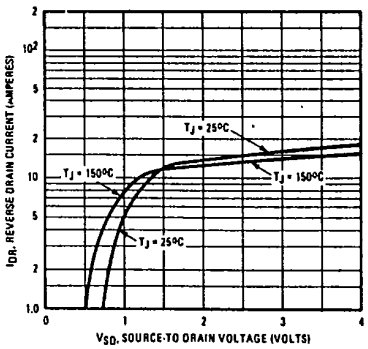

Fig. 7 – Typical Source-Drain Diode Forward Voltage

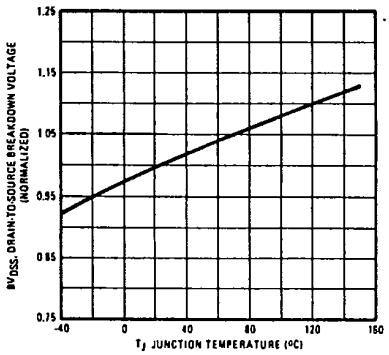

Fig. 8 – Breakdown Voltage Vs. Temperature

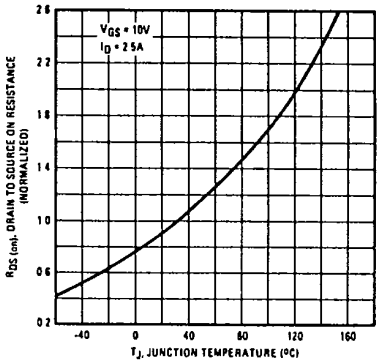

Fig. 9 – Normalized On-Resistance Vs. Temperature

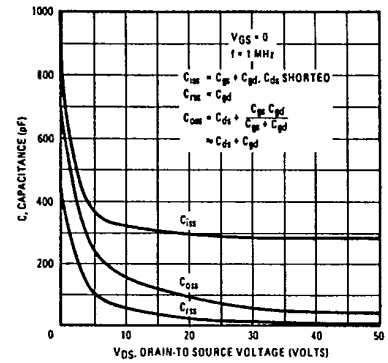

Fig. 10 – Typical Capacitance Vs. Drain-to-Source Voltage

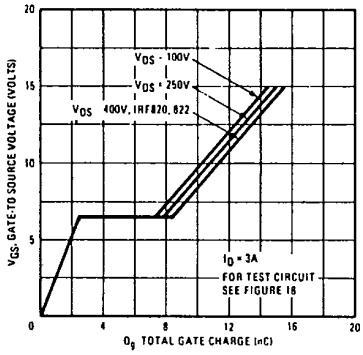

Fig. 11 – Typical Gate Charge Vs. Gate-to-Source Voltage

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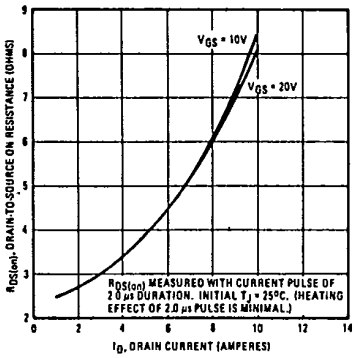

Fig. 12 – Typical On-Resistance Vs. Drain Current

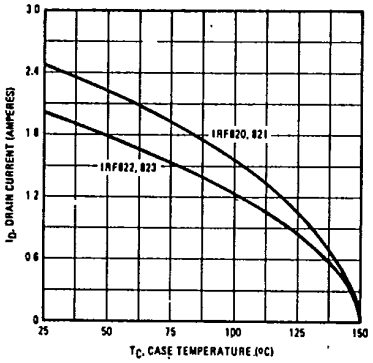

Fig. 13 – Maximum Drain Current Vs. Case Temperature

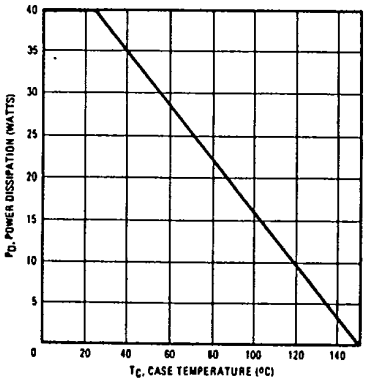

Fig. 14 – Power Vs. Temperature Derating Curve

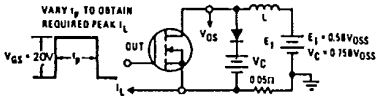

Fig. 15 – Clamped Inductive Test Circuit

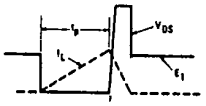

Fig. 16 – Clamped Inductive Waveforms

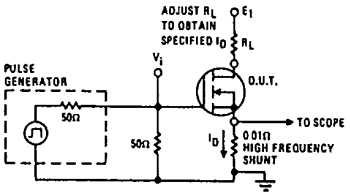

Fig. 17 – Switching Time Test Circuit

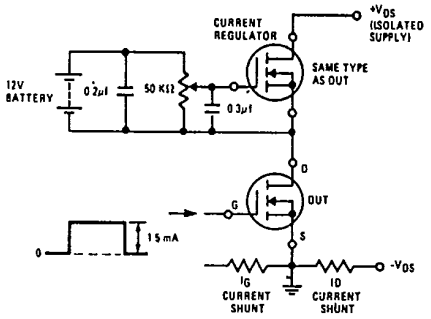

Fig. 18 – Gate Charge Test Circuit